

Vyncolit INSUL-PLATE™ X-28057-2HT Hole-Fill Powder For Printed Circuit Boards

Category : Polymer , Thermoset , Epoxy , Filled/Reinforced Thermoset

Material Notes:

Vyncolit INSUL-PLATE™ Hole-Fill material delivers true reliability and superior performance. This material, in powder form, is specifically suited for Hole-Fill use in glass epoxy, multi-layer and polyimide metal core circuit boards. The material is designed to meet or exceed the higher process and post-cure temperatures required for polyimide prepregs. Vyncolit Hole-Fill powder offers excellent adhesion to the metal core plates while maintaining the required mechanical and electrical properties. In addition, INSUL-PLATE material readily accepts plating with excellent adhesion. Vyncolit monitors the material on a lot-to-lot basis to assure a consistent product and to provide the high reliability required for metal core and multi-layer board applications. Information provided by Sumitomo Bakelite North America, Inc.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Vyncolit-INSUL-PLATE-X-28057-2HT-Hole-Fill-Powder-For-Printed-Circuit-Boards.php

Physical Properties	Metric	English	Comments
Density	1.99 g/cc	0.0719 lb/in ³	As Molded
Water Absorption	0.060 %	0.060 %	ASTM D570
	@Temperature 23.0 °C, Time 86400 sec	@Temperature 73.4 °F, Time 24.0 hour	
	0.20 %	0.20 %	ASTM D570
	@Temperature 50.0 °C, Time 173000 sec	@Temperature 122 °F, Time 48.0 hour	
Linear Mold Shrinkage	0.0060 cm/cm	0.0060 in/in	ASTM D792

Mechanical Properties	Metric	English	Comments
Tensile Strength at Break	51.0 MPa	7400 psi	ASTM D638
Flexural Strength	96.0 MPa	13900 psi	ASTM D790
Flexural Modulus	13.8 GPa	2000 ksi	ASTM D790
Compressive Strength	172 MPa	24900 psi	ASTM D695
Izod Impact, Notched	0.180 J/cm	0.337 ft-lb/in	ASTM D256

Thermal Properties	Metric	English	Comments
CTE, linear	25.0 µm/m-°C	13.9 µin/in-°F	Post Cured; ASTM E831
	@Temperature 40.0 - 125 °C	@Temperature 104 - 257 °F	
	28.0 µm/m-°C	15.6 µin/in-°F	Post Cured; ASTM E831

Thermal Properties	Metric @Temperature 40.0 - 125 °C	English @Temperature 104 - 257 °F	Comments
	29.0 µm/m-°C	16.1 µin/in-°F	As Molded; ASTM E831
	@Temperature 40.0 - 125 °C	@Temperature 104 - 257 °F	
Thermal Conductivity	0.630 W/m-K	4.37 BTU-in/hr-ft²-°F	ASTM C518
Maximum Service Temperature, Air	260 °C	500 °F	
Glass Transition Temp, Tg	177 °C	351 °F	

Electrical Properties	Metric	English	Comments
Volume Resistivity	1.00e+14 ohm-cm	1.00e+14 ohm-cm	ASTM D257
Insulation Resistance	1.00e+15 ohm	1.00e+15 ohm	ASTM D257
Dielectric Constant	5.25	5.25	dry; ASTM D150
	@Frequency 1.00e+6 Hz	@Frequency 1.00e+6 Hz	
Dielectric Strength	13.7 kV/mm	348 kV/in	short time, dry; ASTM D149
Dissipation Factor	0.0080	0.0080	dry; ASTM D150
	@Frequency 1.00e+6 Hz	@Frequency 1.00e+6 Hz	
Arc Resistance	180 sec	180 sec	ASTM D495

Processing Properties	Metric	English	Comments
Processing Temperature	143 - 177 °C	290 - 350 °F	Molding
Mold Temperature	143 - 177 °C	289 - 351 °F	
Shelf Life	>= 6.00 Month	>= 6.00 Month	
	@Temperature 4.44 °C	@Temperature 40.0 °F	

Descriptive Properties	Value	Comments
Color	Black	
Form	Powder	

Contact Songhan Plastic Technology Co.,Ltd.

Website : www.lookpolymers.com

Email : sales@lookpolymers.com

Tel : +86 021-51131842

Mobile : +86 13061808058

Skype : lookpolymers

Address : United North Road 215,Fengxian District, Shanghai City,China